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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Active
Core Processor	ARM926EJ-S
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	400MHz
Co-Processors/DSP	-
RAM Controllers	LPDDR, LPDDR2, DDR2, DDR, SDR, SRAM
Graphics Acceleration	No
Display & Interface Controllers	LCD, Touchscreen
Ethernet	10/100Mbps
SATA	-
USB	USB 2.0 (3)
Voltage - I/O	1.8V, 2.5V, 3.0V, 3.3V
Operating Temperature	-40°C ~ 85°C (TA)
Security Features	-
Package / Case	217-LFBGA
Supplier Device Package	217-LFBGA (15x15)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at91sam9x35-cu-999

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

5.1 Memory Mapping

A first level of address decoding is performed by the AHB Bus Matrix, i.e., the implementation of the Advanced High performance Bus (AHB) for its Master and Slave interfaces with additional features.

Decoding breaks up the 4 Gbytes of address space into 16 banks of 256 Mbytes. Banks 1 to 6 are directed to the EBI that associates these banks to the external chip selects, EBI_NCS0 to EBI_NCS5. Bank 0 is reserved for the addressing of the internal memories, and a second level of decoding provides 1 Mbyte of internal memory area. Bank 15 is reserved for the peripherals and provides access to the Advanced Peripheral Bus (APB).

Other areas are unused and performing an access within them provides an abort to the master requesting such an access.

5.2 Embedded Memories

5.2.1 Internal SRAM

The SAM9X35 embeds a total of 32 Kbytes of high-speed SRAM.

After reset and until the Remap Command is performed, the SRAM is only accessible at address 0x0030 0000.

After Remap, the SRAM also becomes available at address 0x0.

5.2.2 Internal ROM

The SAM9X35 embeds an Internal ROM, which contains the SAM-BA® program.

At any time, the ROM is mapped at address 0x0010 0000. It is also accessible at address 0x0 (BMS = 1) after the reset and before the Remap Command.

5.3 External Memories

5.3.1 External Bus Interface

- Integrates three External Memory Controllers:
 - Static Memory Controller
 - DDR2/SDRAM Controller
 - MLC NAND Flash ECC Controller
- Additional logic for NAND Flash and CompactFlash[®]
- Up to 26-bit Address Bus (up to 64 Mbytes linear per chip select)
- Up to 6 chip selects, Configurable Assignment:
 - Static Memory Controller on NCS0, NCS1, NCS2, NCS3, NCS4, NCS5
 - DDR2/SDRAM Controller (SDCS) or Static Memory Controller on NCS1
 - Optional NAND Flash support on NCS3



12. Advanced Interrupt Controller (AIC)

12.1 Description

The Advanced Interrupt Controller (AIC) is an 8-level priority, individually maskable, vectored interrupt controller, providing handling of up to 32 interrupt sources. It is designed to substantially reduce the software and real-time overhead in handling internal and external interrupts.

The AIC drives the nFIQ (fast interrupt request) and the nIRQ (standard interrupt request) inputs of an ARM processor. Inputs of the AIC are either internal peripheral interrupts or external interrupts coming from the product's pins.

The 8-level Priority Controller allows the user to define the priority for each interrupt source, thus permitting higher priority interrupts to be serviced even if a lower priority interrupt is being treated.

Internal interrupt sources can be programmed to be level sensitive or edge triggered. External interrupt sources can be programmed to be positive-edge or negative-edge triggered or high-level or low-level sensitive.

The Fast Forcing feature redirects any internal or external interrupt source to provide a fast interrupt rather than a normal interrupt.

12.2 Embedded Characteristics

- Controls the Interrupt Lines (nIRQ and nFIQ) of an ARM[®] Processor
- 32 Individually Maskable and Vectored Interrupt Sources
 - Source 0 is Reserved for the Fast Interrupt Input (FIQ)
 - Source 1 is Reserved for System Peripherals
 - Source 2 to Source 31 Control up to 30 Embedded Peripheral Interrupts or External Interrupts
 - Programmable Edge-triggered or Level-sensitive Internal Sources
 - Programmable Positive/Negative Edge-triggered or High/Low Level-sensitive External Sources
- 8-level Priority Controller
 - Drives the Normal Interrupt of the Processor
 - Handles Priority of the Interrupt Sources 1 to 31
 - Higher Priority Interrupts Can Be Served During Service of Lower Priority Interrupt
- Vectoring
 - Optimizes Interrupt Service Routine Branch and Execution
 - One 32-bit Vector Register per Interrupt Source
 - Interrupt Vector Register Reads the Corresponding Current Interrupt Vector
- Protect Mode
 - Easy Debugging by Preventing Automatic Operations when Protect Models Are Enabled
- Fast Forcing
 - Permits Redirecting any Normal Interrupt Source to the Fast Interrupt of the Processor
- General Interrupt Mask
 - Provides Processor Synchronization on Events Without Triggering an Interrupt
- Register Write Protection



12.9.13 AIC End of Interrupt Command Register

Name: AIC_EOICR
Address: 0xFFFFF130
Access: Write-only

31	30	29	28	27	26	25	24
_	_	_	_	_	_	_	_
23	22	21	20	19	18	17	16
_	_	-	-	-		ı	_
15	14	13	12	11	10	9	8
_	_					1	_
7	6	5	4	3	2	1	0
_	_	_	_	_	_	_	ENDIT

• ENDIT: Interrupt Processing Complete Command

The End of Interrupt Command Register is used by the interrupt routine to indicate that the interrupt treatment is complete. Any value can be written because it is only necessary to make a write to this register location to signal the end of interrupt treatment.

12.9.17 AIC Fast Forcing Disable Register

Name: AIC_FFDR
Address: 0xFFFFF144
Access: Write-only

31	30	29	28	27	26	25	24
PID31	PID30	PID29	PID28	PID27	PID26	PID25	PID24
23	22	21	20	19	18	17	16
PID23	PID22	PID21	PID20	PID19	PID18	PID17	PID16
15	14	13	12	11	10	9	8
PID15	PID14	PID13	PID12	PID11	PID10	PID9	PID8
7	6	5	4	3	2	1	0
PID7	PID6	PID5	PID4	PID3	PID2	SYS	_

• SYS: Fast Forcing Disable

0: No effect.

1: Disables the Fast Forcing feature on the corresponding interrupt.

• PID2-PID31: Fast Forcing Disable

0: No effect.

1: Disables the Fast Forcing feature on the corresponding interrupt.

20.5.4 Bypassing the 12 to 16 MHz Crystal Oscillator

Prior to bypassing the 12 to 16 MHz crystal oscillator, the external clock frequency provided on the XIN pin must be stable and within the values specified in the XIN Clock characteristics in the section "Electrical Characteristics".

The sequence to bypass the crystal oscillator is the following:

- 1. Ensure that an external clock is connected on XIN.
- 2. Enable the bypass by setting CKGR MOR.MOSCXTBY.
- Disable the 12 to 16 MHz crystal oscillator by clearing CKGR_MOR.MOSCXTEN.

20.5.5 Main Clock Frequency Counter

The frequency counter is managed by CKGR_MCFR.

During the measurement period, the frequency counter increments at the main clock speed.

A measurement is started in the following cases:

- When the 12 MHz RC oscillator is selected as the source of the main clock and when this oscillator becomes stable (i.e., when the MOSCRCS bit is set)
- When the 12 to 16 MHz crystal oscillator is selected as the source of the main clock and when this oscillator becomes stable (i.e., when the MOSCXTS bit is set)
- When the main clock source selection is modified

The measurement period ends at the 16th falling edge of slow clock, the MAINFRDY bit in the CKGR_MCFR is set and the counter stops counting. Its value can be read in the MAINF field of CKGR_MCFR and gives the number of main clock cycles during 16 periods of slow clock, so that the frequency of the 12 MHz RC oscillator or the crystal oscillator can be determined.

20.5.6 Switching Main Clock Between the RC Oscillator and the Crystal Oscillator

For USB operations an external 12 MHz crystal is required for better accuracy.

The programmer controls the main clock switching by software and so must take precautions during the switching phase.

To switch from internal 12 MHz RC oscillator to the 12 MHz crystal, the programmer must execute the following sequence:

- 1. Enable the 12 MHz oscillator by setting the bit MOSCXTEN to 1.
- 2. Wait that the 12 MHz oscillator status bit MOSCXTS is 1.
- 3. Switch from internal 12 MHz RC oscillator to the 12 MHz oscillator by setting the bit MOSCSEL to 1.
- 4. If not the bit MOSCSEL is set to 0 by the PMC.
- 5. Disable the 12 MHz RC oscillator by setting the bit MOSCRCEN to 0.



BAT: Byte Access Type

This field is used only if DBW defines a 16- or 32-bit data bus.

Value	Name	Description
		Byte select access type:
0	BYTE_SELECT	- Write operation is controlled using NCS, NWE, NBS0, NBS1, NBS2 and NBS3
		- Read operation is controlled using NCS, NRD, NBS0, NBS1, NBS2 and NBS3
		Byte write access type:
1	BYTE_WRITE	- Write operation is controlled using NCS, NWR0, NWR1, NWR2, NWR3
		- Read operation is controlled using NCS and NRD

DBW: Data Bus Width

Value	Name	Description
00	BIT_8	8-bit bus
01	BIT_16	16-bit bus
10	BIT_32	32-bit bus
11	_	Reserved

• TDF_CYCLES: Data Float Time

This field gives the integer number of clock cycles required by the external device to release the data after the rising edge of the read controlling signal. The SMC always provides one full cycle of bus turnaround after the TDF_CYCLES period. The external bus cannot be used by another chip select during TDF_CYCLES + 1 cycles. From 0 up to 15 TDF_CYCLES can be set.

• TDF_MODE: TDF Optimization

1: TDF optimization enabled—The number of TDF wait states is optimized using the setup period of the next read/write access.

0: TDF optimization disabled—The number of TDF wait states is inserted before the next access begins.

• PMEN: Page Mode Enabled

1: Asynchronous burst read in page mode is applied on the corresponding chip select.

0: Standard read is applied.

PS: Page Size

If page mode is enabled, this field indicates the size of the page in bytes.

Value	Name	Description
00	BYTE_4	4-byte page
01	BYTE_8	8-byte page
10	BYTE_16	16-byte page
11	BYTE_32	32-byte page



30.7 DMAC Software Requirements

- There must not be any write operation to channel registers in an active channel after the channel enable is made HIGH. If any channel parameters must be reprogrammed, this can only be done after disabling the DMAC channel.
- The channel registers DMAC_SADDRx and DMAC_DADDRx must be programmed with a byte, half-word and word aligned address depending on the source width and destination width.
- After the software disables a channel by writing into the DMAC Channel Handler Disable Register, it must reenable the channel only after it has polled a '0' in the DMAC Channel Handler Status Register. This is
 because the current AHB Burst must terminate properly.
- If the value of field DMAC_CTRLAx.BTSIZE is configured to zero and the DMAC has been defined as the flow controller, the channel is automatically disabled.
- Multiple transfers involving the same peripheral must not be programmed and enabled on different channels, unless this peripheral integrates several hardware handshaking interfaces.
- When a peripheral has been defined as the flow controller, the targeted DMAC channel must be enabled before the peripheral. If you do not ensure this and the first DMAC request is also the last transfer, the DMAC channel might miss a Last Transfer Flag.
- When the AUTO bit is set to TRUE, the BTSIZE field is automatically reloaded from its previous value.
 BTSIZE must be initialized to a non zero value if the first transfer is initiated with the AUTO bit set to TRUE, even if LLI mode is enabled, because the LLI fetch operation will not update this field.



31.7.24 UDPHS DMA Channel Control Register

Name: UDPHS_DMACONTROLx [x = 0..5]

Address: 0xF803C308 [0], 0xF803C318 [1], 0xF803C328 [2], 0xF803C338 [3], 0xF803C348 [4], 0xF803C358 [5]

Access: Read/Write

31	30	29	28	27	26	25	24
			BUFF_L	ENGTH			
23	22	21	20	19	18	17	16
			BUFF_L	ENGTH			
15	14	13	12	11	10	9	8
_	_	_	_	_	_	_	_
7	6	5	4	3	2	1	0
BURST_LCK	DESC_LD_IT	END_BUFFIT	END_TR_IT	END_B_EN	END_TR_EN	LDNXT_DSC	CHANN_ENB

Note: Channel 0 is not used.

• CHANN ENB: (Channel Enable Command)

0: DMA channel is disabled at and no transfer will occur upon request. This bit is also cleared by hardware when the channel source bus is disabled at end of buffer.

If the UDPHS_DMACONTROL register LDNXT_DSC bit has been cleared by descriptor loading, the firmware will have to set the corresponding CHANN_ENB bit to start the described transfer, if needed.

If the UDPHS_DMACONTROL register LDNXT_DSC bit is cleared, the channel is frozen and the channel registers may then be read and/or written reliably as soon as both UDPHS_DMASTATUS register CHANN_ENB and CHANN_ACT flags read as 0.

If a channel request is currently serviced when this bit is cleared, the DMA FIFO buffer is drained until it is empty, then the UDPHS DMASTATUS register CHANN ENB bit is cleared.

If the LDNXT_DSC bit is set at or after this bit clearing, then the currently loaded descriptor is skipped (no data transfer occurs) and the next descriptor is immediately loaded.

1: UDPHS_DMASTATUS register CHANN_ENB bit will be set, thus enabling DMA channel data transfer. Then any pending request will start the transfer. This may be used to start or resume any requested transfer.

LDNXT_DSC: Load Next Channel Transfer Descriptor Enable (Command)

0: No channel register is loaded after the end of the channel transfer.

1: The channel controller loads the next descriptor after the end of the current transfer, i.e., when the UDPHS_DMASTATUS/CHANN_ENB bit is reset.

If the UDPHS_DMA CONTROL/CHANN_ENB bit is cleared, the next descriptor is immediately loaded upon transfer request.

DMA Channel Control Command Summary

LDNXT_DSC	CHANN_ENB	Description
0	0	Stop now
0	1	Run and stop at end of buffer
1	0	Load next descriptor now
1	1	Run and link at end of buffer



31.7.25 UDPHS DMA Channel Status Register

Name: UDPHS_DMASTATUSx [x = 0..5]

Address: 0xF803C30C [0], 0xF803C31C [1], 0xF803C32C [2], 0xF803C33C [3], 0xF803C34C [4], 0xF803C35C [5]

Access: Read/Write

A00033.	read/vine						
31	30	29	28	27	26	25	24
			BUFF_0	COUNT			
23	22	21	20	19	18	17	16
			BUFF_0	COUNT			
15	14	13	12	11	10	9	8
_	_	-	_	_	_	_	-
7	6	5	4	3	2	1	0
_	DESC_LDST	END_BF_ST	END_TR_ST	-	_	CHANN_ACT	CHANN_ENB

Note: Channel 0 is not used.

• CHANN ENB: Channel Enable Status

0: The DMA channel no longer transfers data, and may load the next descriptor if the UDPHS_DMACONTROLx register LDNXT_DSC bit is set.

When any transfer is ended either due to an elapsed byte count or a UDPHS device initiated transfer end, this bit is automatically reset.

1: The DMA channel is currently enabled and transfers data upon request.

This bit is normally set or cleared by writing into the UDPHS_DMACONTROLx register CHANN_ENB bit either by software or descriptor loading.

If a channel request is currently serviced when the UDPHS_DMACONTROLx register CHANN_ENB bit is cleared, the DMA FIFO buffer is drained until it is empty, then this status bit is cleared.

CHANN ACT: Channel Active Status

0: The DMA channel is no longer trying to source the packet data.

When a packet transfer is ended this bit is automatically reset.

1: The DMA channel is currently trying to source packet data, i.e., selected as the highest-priority requesting channel.

When a packet transfer cannot be completed due to an END_BF_ST, this flag stays set during the next channel descriptor load (if any) and potentially until UDPHS packet transfer completion, if allowed by the new descriptor.

END TR ST: End of Channel Transfer Status

0: Cleared automatically when read by software.

1: Set by hardware when the last packet transfer is complete, if the UDPHS device has ended the transfer.

Valid until the CHANN ENB flag is cleared at the end of the next buffer transfer.

• END_BF_ST: End of Channel Buffer Status

0: Cleared automatically when read by software.

1: Set by hardware when the BUFF COUNT downcount reach zero.

Valid until the CHANN_ENB flag is cleared at the end of the next buffer transfer.



35.6 Functional Description

35.6.1 Description

All channels of the Timer Counter are independent and identical in operation. The registers for channel programming are listed in Table 35-6 "Register Mapping".

35.6.2 32-bit Counter

Each 32-bit channel is organized around a 32-bit counter. The value of the counter is incremented at each positive edge of the selected clock. When the counter has reached the value 2³²-1 and passes to zero, an overflow occurs and the COVFS bit in the TC Status Register (TC SR) is set.

The current value of the counter is accessible in real time by reading the TC Counter Value Register (TC_CV). The counter can be reset by a trigger. In this case, the counter value passes to zero on the next valid edge of the selected clock.

35.6.3 Clock Selection

At block level, input clock signals of each channel can either be connected to the external inputs TCLK0, TCLK1 or TCLK2, or be connected to the internal I/O signals TIOA0, TIOA1 or TIOA2 for chaining by programming the TC Block Mode Register (TC_BMR). See Figure 35-2.

Each channel can independently select an internal or external clock source for its counter:

- External clock signals⁽¹⁾: XC0, XC1 or XC2
- Internal clock signals: MCK/2, MCK/8, MCK/32, MCK/128, SLCK

This selection is made by the TCCLKS bits in the TC Channel Mode Register (TC CMR).

The selected clock can be inverted with the CLKI bit in the TC_CMR. This allows counting on the opposite edges of the clock.

The burst function allows the clock to be validated when an external signal is high. The BURST parameter in the TC_CMR defines this signal (none, XC0, XC1, XC2). See Figure 35-3.

te: 1. In all cases, if an external clock is used, the duration of each of its levels must be longer than the peripheral clock period. The external clock frequency must be at least 2.5 times lower than the peripheral clock.

Figure 35-2. Clock Chaining Selection

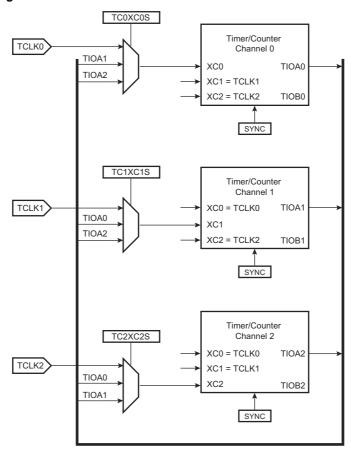
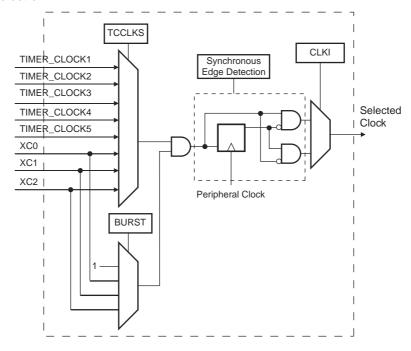


Figure 35-3. Clock Selection





41. Analog-to-Digital Converter (ADC)

41.1 Description

The ADC is based on a 10-bit Analog-to-Digital Converter (ADC) managed by an ADC Controller. Refer to Figure 41-1 "Analog-to-Digital Converter Block Diagram with Touchscreen Mode". It also integrates a 12-to-1 analog multiplexer, making possible the analog-to-digital conversions of 12 analog lines. The conversions extend from 0V to the voltage carried on pin ADVREF.

The ADC digital controller embeds circuitry to reduce the resolution down to 8 bits. The 8-bit resolution mode prevents using 16-bit Peripheral DMA transfer into memory when only 8-bit resolution is required by the application. Note that using this low resolution mode does not increase the conversion rate.

Conversion results are reported in a common register for all channels, as well as in a channel-dedicated register.

Software trigger, external trigger on rising edge of the ADTRG pin or internal triggers from Timer Counter output(s) are configurable.

The comparison circuitry allows automatic detection of values below a threshold, higher than a threshold, in a given range or outside the range, thresholds and ranges being fully configurable.

The ADC also integrates a Sleep mode and a conversion sequencer and connects with a DMA channel. These features reduce both power consumption and processor intervention.

Finally, the user can configure ADC timings, such as startup time and tracking time.

This ADC Controller includes a Resistive Touchscreen Controller. It supports 4-wire and 5-wire technologies.

41.2 Embedded Characteristics

- 10-bit Resolution
- 440 kHz Conversion Rate
- Wide Range of Power Supply Operation
- Resistive 4-wire and 5-wire Touchscreen Controller
 - Position and Pressure Measurement for 4-wire Screens
 - Position Measurement for 5-wire Screens
 - Average of Up to 8 Measures for Noise Filtering
- Programmable Pen Detection Sensitivity
- Integrated Multiplexer Offering Up to 12 Independent Analog Inputs
- Individual Enable and Disable of Each Channel
- Hardware or Software Trigger
 - External Trigger Pin
 - Internal Trigger Counter
 - Trigger on Pen Contact Detection
- DMA Support
- Possibility of ADC Timings Configuration
- Two Sleep Modes and Conversion Sequencer
 - Automatic Wakeup on Trigger and Back to Sleep Mode after Conversions of all Enabled Channels
 - Possibility of Customized Channel Sequence
- Standby Mode for Fast Wakeup Time Response
 - Power Down Capability
- Automatic Window Comparison of Converted Values
- Register Write Protection



44.6.26.3 Single Collision Frames Register

Name: EMAC_SCF
Address: 0xF802C044
Access: Read-write

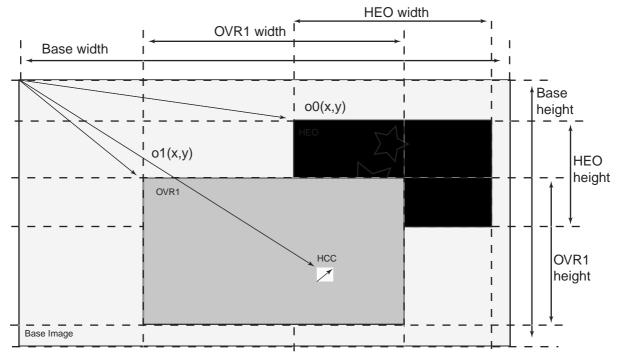
, ,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	riodd irriio						
31	30	29	28	27	26	25	24
_	-	_	-	-	-	-	-
23	22	21	20	19	18	17	16
_	_	_	_	_	_	_	_
15	14	13	12	11	10	9	8
			S	CF			
7	6	5	4	3	2	1	0
			S	CF			

• SCF: Single Collision Frames

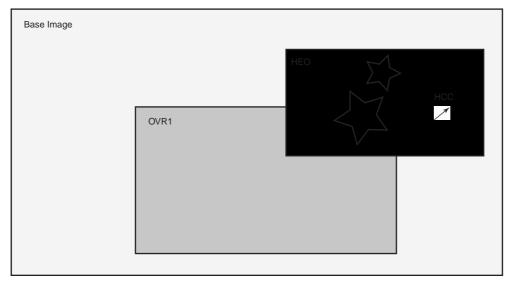
A 16-bit register counting the number of frames experiencing a single collision before being successfully transmitted, i.e., no underrun.



Figure 45-6. Overlay Example with two different video prioritization algorithms



Video Prioritization Algorithm 1: HCC > OVR1 > HEO > BASE

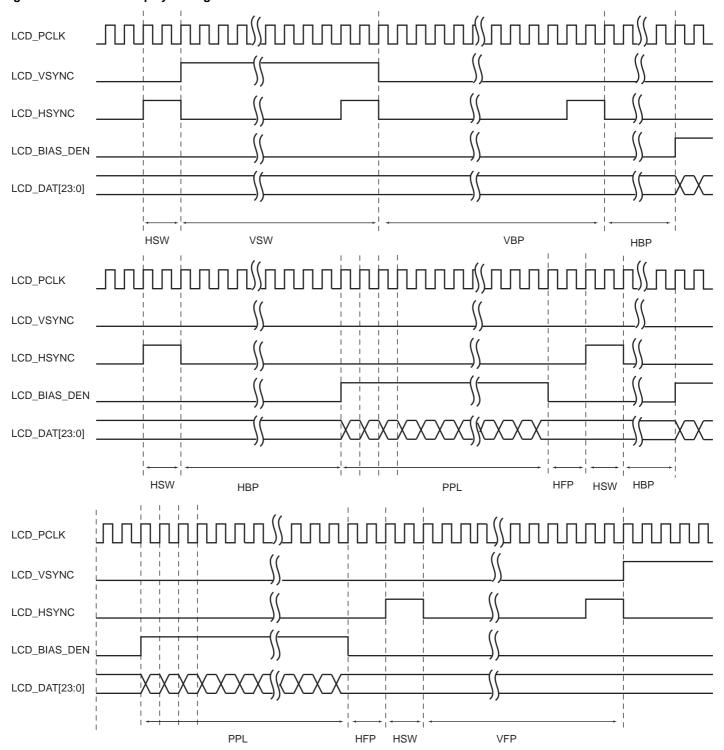


Video Prioritization Algorithm 2: HCC > HEO > OVR1 > BASE

45.6.13 Output Timing Generation

45.6.13.1 Active Display Timing Mode

Figure 45-11. Active Display Timing



45.7.6 LCD Controller Configuration Register 5

Name: LCDC LCDCFG5

Address: 0xF8038014

Access: Read/Write

31	30	29	28	27	26	25	24	
_	-	_	_	_	-	_	_	
23	22	21	20	19	18	17	16	
_	_	_	GUARDTIME					
15	14	13	12	11	10	9	8	
_	_	VSPHO	VSPSU	_	_	MODE		
7	6	5	4	3	2	1	0	
DISPDLY	DITHER	_	DISPPOL	VSPDLYE	VSPDLYS	VSPOL	HSPOL	

. HSPOL: Horizontal Synchronization Pulse Polarity

0: Active High

1: Active Low

• VSPOL: Vertical Synchronization Pulse Polarity

0: Active High

1: Active Low

VSPDLYS: Vertical Synchronization Pulse Start

0: The first active edge of the Vertical synchronization pulse is synchronous with the second edge of the horizontal pulse.

1: The first active edge of the Vertical synchronization pulse is synchronous with the first edge of the horizontal pulse.

VSPDLYE: Vertical Synchronization Pulse End

0: The second active edge of the Vertical synchronization pulse is synchronous with the second edge of the horizontal pulse.

1: The second active edge of the Vertical synchronization pulse is synchronous with the first edge of the horizontal pulse.

• DISPPOL: Display Signal Polarity

0: Active High

1: Active Low

DITHER: LCD Controller Dithering

0: Dithering logical unit is disabled.

1: Dithering logical unit is activated.

• DISPDLY: LCD Controller Display Power Signal Synchronization

0: the LCD_DISP signal is asserted synchronously with the second active edge of the horizontal pulse.

1: the LCD DISP signal is asserted asynchronously with both edges of the horizontal pulse.



45.7.45 Overlay 1 Layer Configuration 3 Register

Name: LCDC_OVR1CFG3

Address: 0xF8038138
Access: Read/Write

31	30	29	28	27	26	25	24			
_	_	_	_	_		YSIZE				
23	22	21	20	19	18	17	16			
	YSIZE									
15	14	13	12	11	10	9	8			
_	_	_	_	_		XSIZE				
7	6	5	4	3	2	1	0			
	XSIZE									

• XSIZE: Horizontal Window Size

Overlay 1 window width in pixels. The window width is set to (XSIZE + 1).

The following constraint must be met: XPOS + XSIZE ≤PPL

• YSIZE: Vertical Window Size

Overlay 1 window height in pixels. The window height is set to (YSIZE + 1).

The following constrain must be met: YPOS + YSIZE ≤RPF



45.7.56 High End Overlay Layer Interrupt Disable Register

Name: LCDC_HEOIDR
Address: 0xF8038290
Access: Write-only

31	30	29	28	27	26	25	24
_	-	-	_	-	_	_	_
23	22	21	20	19	18	17	16
_	VOVR	VDONE	VADD	VDSCR	VDMA	_	_
15	14	13	12	11	10	9	8
_	UOVR	UDONE	UADD	UDSCR	UDMA	_	-
7	6	5	4	3	2	1	0
_	OVR	DONE	ADD	DSCR	DMA	_	_

• DMA: End of DMA Transfer Interrupt Disable Register

0: No effect.

1: Interrupt source is disabled.

DSCR: Descriptor Loaded Interrupt Disable Register

0: No effect.

1: Interrupt source is disabled.

• ADD: Head Descriptor Loaded Interrupt Disable Register

0: No effect.

1: Interrupt source is disabled.

. DONE: End of List Interrupt Disable Register

0: No effect.

1: Interrupt source is disabled.

• OVR: Overflow Interrupt Disable Register

0: No effect.

1: Interrupt source is disabled.

• UDMA: End of DMA Transfer for U or UV Chrominance Component Interrupt Disable Register

0: No effect.

1: Interrupt source is disabled.

• UDSCR: Descriptor Loaded for U or UV Chrominance Component Interrupt Disable Register

0: No effect.

1: Interrupt source is disabled.

UADD: Head Descriptor Loaded for U or UV Chrominance Component Interrupt Disable Register

0: No effect.

1: Interrupt source is disabled.

45.7.109 Overlay 1 CLUT Register x Register

Name: LCDC_OVR1CLUTx [x=0..255]

Address: 0xF8038800 Access: Read/Write

31	30	29	28	27	26	25	24	
ACLUT								
23	22	21	20	19	18	17	16	
RCLUT								
15	14	13	12	11	10	9	8	
GCLUT								
7	6	5	4	3	2	1	0	
BCLUT								

• BCLUT: Blue Color entry

This field indicates the 8-bit width Blue color of the color lookup table.

GCLUT: Green Color entry

This field indicates the 8-bit width Green color of the color lookup table.

• RCLUT: Red Color entry

This field indicates the 8-bit width Red color of the color lookup table.

ACLUT: Alpha Color entry

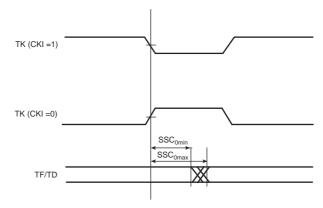
This field indicates the 8-bit width Alpha channel of the color lookup table.

Table 46-43. SSC Timings - 3.3V Peripheral Supply

Symbol	Parameter	Conditions	Min	Max	Unit
		Transmitter			+
SSC ₀	TK edge to TF/TD (TK output, TF output)		-4.6 ⁽¹⁾	4.9 ⁽¹⁾	ns
SSC ₁	TK edge to TF/TD (TK input, TF output)		2.3 ⁽¹⁾	11.4 ⁽¹⁾	ns
SSC ₂	TF setup time before TK edge (TK output)		9.9		ns
SSC ₃	TF hold time after TK edge (TK output)		0		ns
SSC ₄			-4.6 ⁽¹⁾	4.7 (1)	ns
	TK edge to TD (TK output, TF input)	STTDLY = 0 START = 4, 5 or 7	-4.6 (+2 × t _{CPMCK}) ⁽¹⁾	4.7 (+2 × t _{CPMCK}) ⁽¹⁾	
SSC ₅	TF setup time before TK edge (TK input)		0		ns
SSC ₆	TF hold time after TK edge (TK input)		t _{CPMCK}		ns
			2.3 (1)	11.1 ⁽¹⁾	ns
SSC ₇	TK edge to TD (TK input, TF input)	STTDLY = 0 START = 4, 5 or 7	2.3 (+3 × t _{CPMCK}) ⁽¹⁾	11.1 (+3 × t _{CPMCK}) ⁽¹⁾	
		Receiver			
SSC ₈	RF/RD setup time before RK edge (RK input)		0		ns
SSC ₉	RF/RD hold time after RK edge (RK input)		t _{CPMCK}		ns
SSC ₁₀	RK edge to RF (RK input)		2.0 ⁽¹⁾	10.9 ⁽¹⁾	ns
SSC ₁₁	RF/RD setup time before RK edge (RK output)		10.0 - t _{CPMCK}		ns
SSC ₁₂	RF/RD hold time after RK edge (RK output)		t _{CPMCK} - 1.8		ns
SSC ₁₃	RK edge to RF (RK output)		-4.9 ⁽¹⁾	4.3 ⁽¹⁾	ns

Notes: 1. For output signals (TF, TD, RF), minimum and maximum access times are defined. The minimum access time is the time between the TK (or RK) edge and the signal change. The maximum access time is the time between the TK edge and the signal stabilization. Figure 46-24 illustrates minimum and maximum accesses for SSC0. The same applies to SSC1, SSC4, and SSC7, SSC10 and SSC13.

Figure 46-24. Minimum and Maximum Access Time of Output Signals



46.18.3 HSMCI

The High Speed MultiMedia Card Interface (HSMCI) supports the MultiMedia Card (MMC) Specification V4.3, the SD Memory Card Specification V2.0, the SDIO V2.0 specification and CE-ATA V1.1.

